

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L14	16	(die or chip or ic or semiconductor near device or pellet) near8 (mounted or bonded or attached or post-mounting or post-attachment or post-bonding) near8 (position\$4 or locat\$4 or align\$4 or registrat\$4) near8 (view or visual) near2 (field or area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 13:34
L12	70	(die or chip or ic or semiconductor near device or pellet) near2 (mounted or bonded or attached or post-mounting or post-attachment or post-bonding) near4 (inspect\$4 or monitor\$4 or detect\$4) same (position\$4 or locat\$4 or align\$4 or registrat\$4) near10 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 13:32
L10	254	(die or chip or ic or semiconductor near device) near2 (mount\$4 or bond\$4 or attach\$4) and (mounted or bonded or attached or post-mounting or post-attachment or post-bonding) near4 (inspect\$4 or monitor\$4 or detect\$4) same (position\$4 or locating or location\$4 or align\$4 or registrat\$4) near10 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 13:06
L9	2	(die or chip or ic or semiconductor near device) near2 (mount\$4 or bond\$4 or attach\$4) and (mounted or bonded or attached or post-mounting or post-attachment or post-bonding) near4 (inspect\$4 or monitor\$4 or detect\$4) near8 (during or while or "same" near time) near8 (position\$4 or locating or location\$4 or align\$4 or registrat\$4) near10 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 13:04

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L7	13	(die or chip or ic or semiconductor near device) near2 (mount\$4 or bond\$4 or attach\$4) and (mounted or bonded or attached or post-mounting or post-attachment or post-bonding) near4 (inspect\$4 or monitor\$4 or detect\$4) near8 (single or solo or only or alone or simultaneous\$3 or "one") near8 (position\$4 or locating or location\$4 or align\$4 or registrat\$4) near10 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 13:02
L5	199	(die or chip or ic or semiconductor near device) near2 (mount\$4 or bond\$4 or attach\$4) and (mount\$4 or bond\$4 or attach\$4) near4 (inspect\$4 or monitor\$4 or detect\$4) near4 (image or imaging or imaged or imager or ccd or camera or photo or photograph or photographing) same (position\$4 or locating or location\$4 or align\$4 or registrat\$4) near4 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 12:54
L2	481	(die or chip or ic or semiconductor near device) same (mount\$4 or bond\$4 or attach\$4) near4 (inspect\$4 or monitor\$4 or detect\$4) near8 (image or imaging or imaged or imager or ccd or camera or photo or photograph or photographing) and (position\$4 or locating or location\$4 or align\$4 or registrat\$4) near8 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 12:42
L1	7380	(mount\$4 or bond\$4 or attach\$4) near4 (inspect\$4 or monitor\$4 or detect\$4) near8 (image or imaging or imaged or imager or ccd or camera or photo or photograph or photographing) and (position\$4 or locating or location\$4 or align\$4 or registrat\$4) near8 (image or imaging or imager or imaged or ccd or camera or photo or photograph or photographing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 12:41

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S59	11	"20030029033" "5946409".pn. "20010051394" "6389688".pn. "20030110623"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 12:37
S58	547	382/149.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:00
S57	122	29/836.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 14:00
S56	545	29/834.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 13:51
S55	494	29/833.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:58
S54	64	438/111.ccls. and (camera or imager or imaging or ccd or detector or sensor or recorder or monitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:35
S53	437	438/111.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:34
S52	107	438/110.ccls. and (camera or imager or imaging or ccd or detector or sensor or recorder or monitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:34

EAST Search History

S51	274	438/108.ccls. and (camera or imager or imaging or ccd or detector or sensor or recorder or monitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 11:40
S50	250	438/107.ccls. and (camera or imager or imaging or ccd or detector or sensor or recorder or monitor)	US-PGPUB; USPAT	OR	ON	2006/03/09 11:02
S49	201	(die or chip or ic or integrated adj circuit or semiconductor near device or solid near device) near3 (bonding or bond or bonded or bonder or attachment or attaching or attach or mounting or mounted or mounter or affixing or sealing or joining or joiner or attached) near15 (imager or camera or ccd) near4 (inspection or inspecting or inspected or monitor or monitoring or detector or detected)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 10:44
S48	248	(chip or die or ic or integrated adj circuit or semiconductor near device) near6 (bonding or bond or bonder or attacher or mounter or attachment or attach or attaching or mount or mounting or mounted or affixing or adhering) same (plural or plurality or multiple or multi or two or "next" or adjacent or neighbor or neighboring) near3 (chip or die or ic or circuit or device) near6 (camera or ccd or imager or imaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 10:21
S47	256	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near6 (visual or view or vision) near (field) near10 (location or position or inspecting or inspection or detection or detecting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 09:51
S46	112	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near3 (inspection or inspecting or inspect or testing or test or examination or examining or check or checking or monitor or monitoring) near3 (mounted or post or after or attached or bonded)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 09:41

EAST Search History

S45	216	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera or ccd) near (single)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 09:19
S44	8	"5586010".pn. "5821608".pn. "5831836".pn. "5239131".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 09:14
S43	91	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) near10 (wiring near board or substrate or interposer or circuit adj board or pcb or pwb or carrier) and (imager or camera or ccd) near6 (visual or view or vision) near (field) near10 (location or position or inspecting or inspection or detection or detecting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 09:13
S42	100	(die or chip or ic or integrated adj circuit) near3 (bonding or bond or attachment or attaching or mounting or mounted or bonded or attached) and (imager or camera) near6 (inspection or inspecting or test or testing) near10 (position or positioning or location or locating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 08:46

Interference Search

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L15	80	((die or chip or ic or pellet or semiconductor near device) near2 (mount\$4 or attach\$4 or bond\$4) and (inspect\$4 or detect\$4 or test\$4 or position\$4 or locat\$4 or registrat\$4 or align\$4) near4 (camera or imager or ccd)).clm.	US-PGPUB	OR	ON	2006/03/13 13:49
L16	5	((die or chip or ic or pellet or semiconductor near device) near2 (mounted or bonded or attached or (after or post) near (bonding or attachment or attaching or mounting)) near20 (inspect\$4 or detect\$4 or test\$4 or position\$4 or locat\$4 or registrat\$4 or align\$4) near4 (camera or imager or ccd)).clm.	US-PGPUB	OR	ON	2006/03/13 13:49
L17	45	((die or chip or ic or pellet or semiconductor near device) near2 (mount\$4 or attach\$4 or bond\$4) and (imager or camera or ccd) near2 (field or area or region) near2 (visual or view)).clm.	US-PGPUB	OR	ON	2006/03/13 13:52
L18	57	((die or chip or ic or pellet or semiconductor near device) near2 (mount\$4 or attach\$4 or bond\$4) and (imager or camera or ccd or imaging or imaged) near2 (single or solo or alone or only or one or once)).clm.	US-PGPUB	OR	ON	2006/03/13 14:04
L19	60	((die or chip or ic or pellet or semiconductor near device) near2 (mount\$4 or attach\$4 or bond\$4) and (imager or camera or ccd or imaging or imaged) near3 (position\$4 or locat\$4 or registration or align\$4) and (ccd or imager or camera or imaging or imaged) near3 (bonded or mounted or attached or after or post or completed)).clm.	US-PGPUB	OR	ON	2006/03/13 14:09
L20	313	438/107.ccls.	US-PGPUB	OR	ON	2006/03/13 14:09